

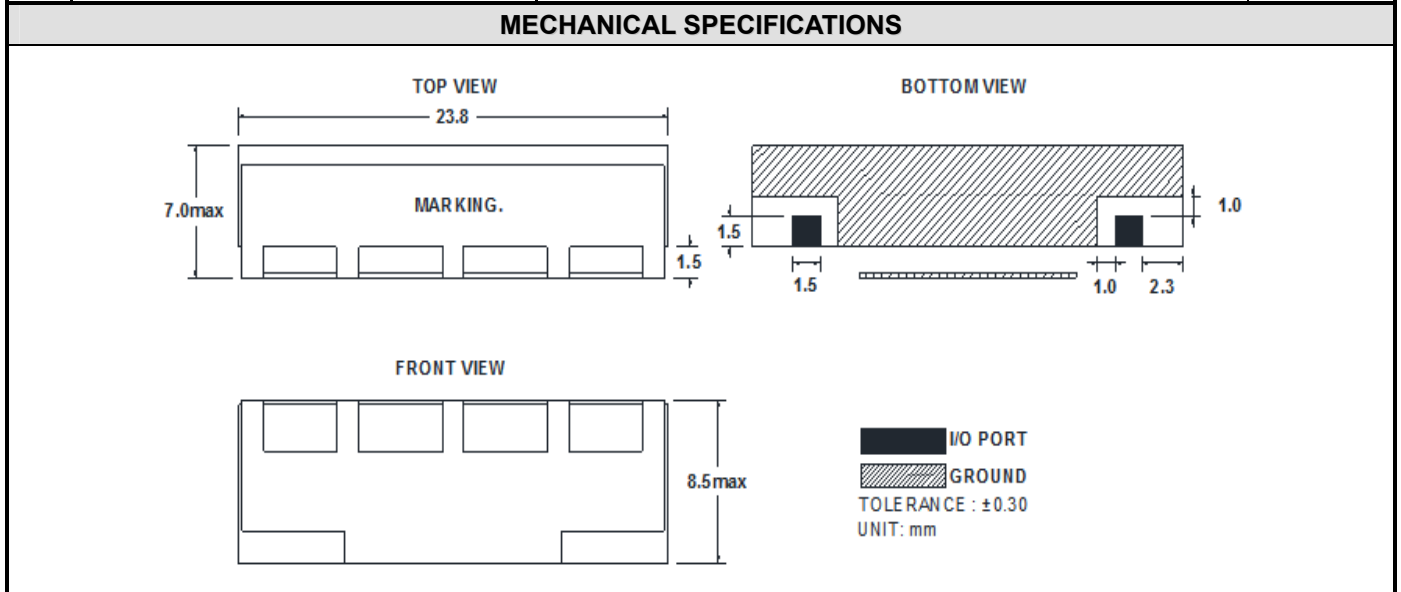
# SPECIFICATION



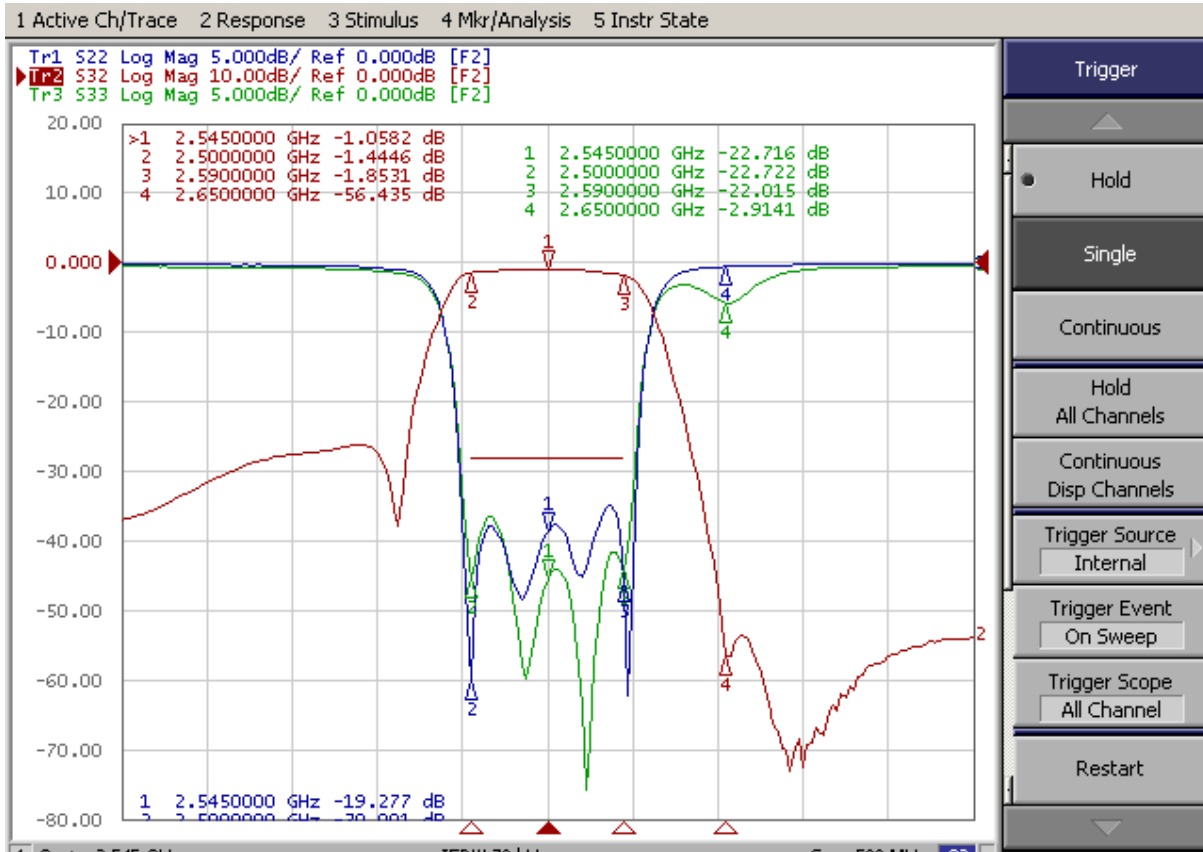
Part No.: \_\_\_\_\_  
 Customer: \_\_\_\_\_  
 Date: 2021.10.20  
 Lot No.:20210177-1 Q'ty: 50pcs

Written by	Checked by	Approval
FL Lai	MY Chen	CK Chang

ELECTRICAL SPECIFICATIONS		
ITEM	SPEC	UNIT
1	Center Frequency [fo]	2545
2	Bandwidth [BW]	$fo \pm 45 [ 2500.0 \sim 2590.0 ]$
3	Insertion Loss @ BW	2.0 max
4	Ripple in BW	1.0 max
5	V.S.W.R in BW	1.5 max
6	Attenuation	50.0 min. @ $fo \pm [ 2650.0 \sim ]$ MHz
7	In/Out Impedance	50
8	Operation Temperature Range	-40°C to +70°C



### PERFORMANCE



## REFLOW SOLDERING STANDARD CONDITION

1. Please ensure a good ground(area between GROUND and I/O PORT) is ready when you use the PCB packaging product. In order to do so, please repair welding for the lateral pin after welding the bottom area.
2. SMT is recommended to you for using this product. The graph below shows recommendatory reflow profile. Since the performance between the substrate and the reflow is different, please refer to the both devices to confirm the actual temperature profile.
3. Soldering can only be for PCB packaging product, and therefore it is forbidden to be used for ceramic dielectric product.

